Docket No.: **SEC.770**

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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

OIPE
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JC147
PATENT & TRADEMARK OFFICE

1. Name of conveying party(ies):

PARK, Myun-Joo
SO, Byung-Se
LEE, Sang-Won
LEE, Dong-Ho

Additional names(s) of conveying party(ies) ☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: **SAMSUNG ELECTRONICS CO., LTD.**

Address: **416, Maetan-dong, Paldal-gu,**

City: **Suwon-city, Kyungki-do** State/Prov.:

Country: **Republic of Korea** ZIP:

Additional name(s) & address(es) ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: **March 29, 29, 29, 30, 2001**

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is:

Patent Application No.	Filing date	B. Patent No.(s)
09/799,094	**03/06/2001**	

Additional numbers ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **ADAM C. VOLENTINE**

Registration No. **33289**

Address: **JONES VOLENTINE, PLLC**
12200 SUNRISE VALLEY DRIVE, SUITE 150

City: **RESTON** State/Prov.: **VA**

Country: **U.S.A.** ZIP: **20191**

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 3.41):..................$ **40.00**

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account

☐ Authorized to be charged to deposit account

8. Deposit account number:

50-0238

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[illegible]

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

ADAM C. VOLENTINE		**MAY 31, 2001**
Name of Person Signing	Signature	Date

Total number of pages including cover sheet, attachments, and **3**

ASSIGNMENT

In consideration of the sum of One Dollar ($1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s) of Inventor(s)

PARK, Myun-Joo

SO, Byung-Se

LEE, Sang-Won

LEE, Dong-Ho

Insert Name(s) of Assignee(s)

the undersigned hereby sell(s) and assign(s) to

SAMSUNG ELECTRONICS CO., LTD.

Address

of 416, Maetan-dong, Paldal-gu, Suwon-city, Kyunggi-do, Republic of Korea

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Title of Invention

CHIP SCALE PACKAGE, PRINTED CIRCUIT BOARD, AND METHOD OF DESIGNING A PRINTED CIRCUIT BOARD

Date of Signing of Application

for which an application for patent in the United States of America has been executed by the undersigned

on ____________________

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) to Adam C. Volentine, Reg. No. 33,289, and the firm of JONES VOLENTINE, L.L.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date Mar. 29, 2001, Name of Inventor Myun-Joo Park
Myun-Joo PARK

Date Mar. 29, 2001, Name of Inventor BYUNG SE SO
Byung-Se SO

Date Mar. 29, 2001, Name of Inventor Sang-won Lee
Sang-Won LEE

Date Mar 30, 2001, Name of Inventor
Dong-Ho LEE

Date __________, Name of Inventor __________

(**Note regarding Witnessing and/or Acknowledgment:** Acknowledgment before a United States Consul is preferred but not required. If not acknowledged, then it is recommended that the execution by the Inventor(s) be witnessed by at least two witnesses who sign here. However, the current practice of the U.S. Patent and Trademark Office is to record an Assignment even if it has not been acknowledged and/or witnessed.)

Witness __________

Witness __________

ACKNOWLEDGMENT

__________ }
__________ } ss

This ________ day of __________, 19___, before me personally came the above-named __________

to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

____
Official Signature

SEAL

____
Official Title

* * *

Applicant Reference No.: 2000008-007 Atty Docket No.: SEC.770

Serial No.: 09/799,094 Filing Date: MARCH 6, 2001